

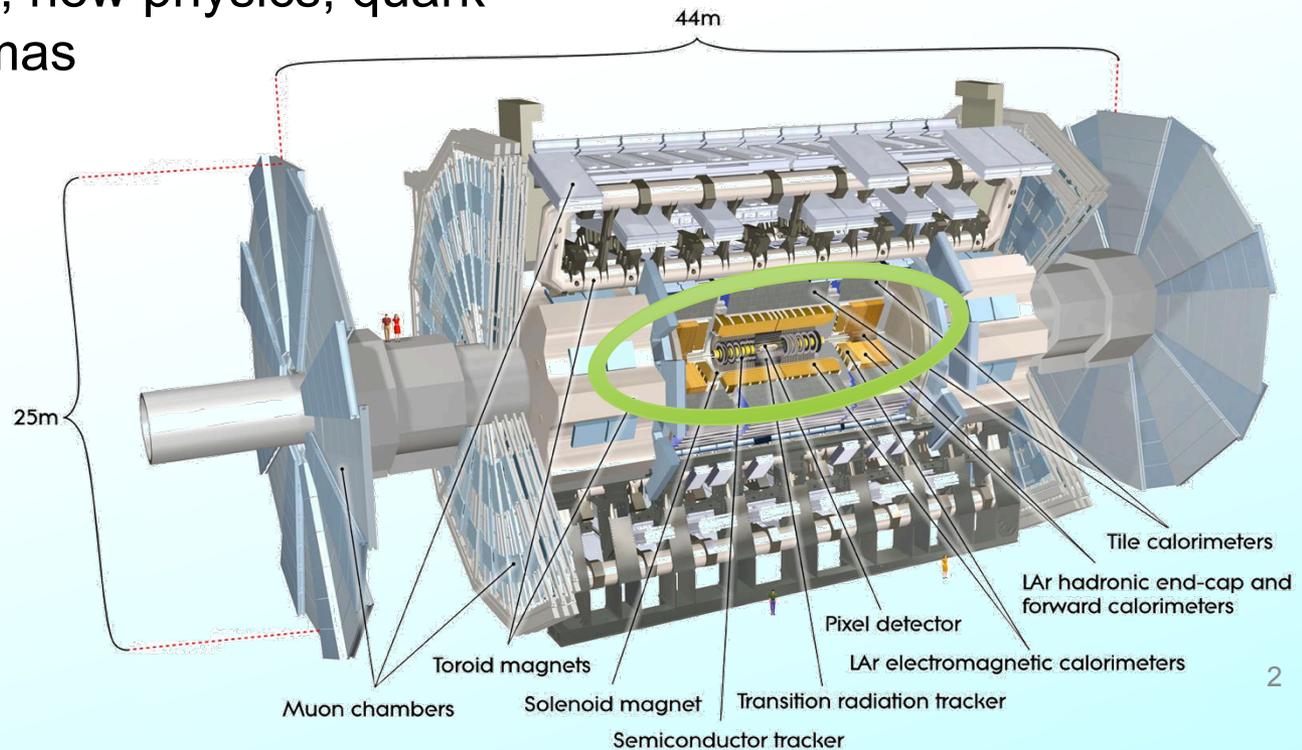


PROPOSED CMOS-BASED SENSORS FOR THE ATLAS DETECTOR: CHESS-2

Robin Newhouse
University of British Columbia

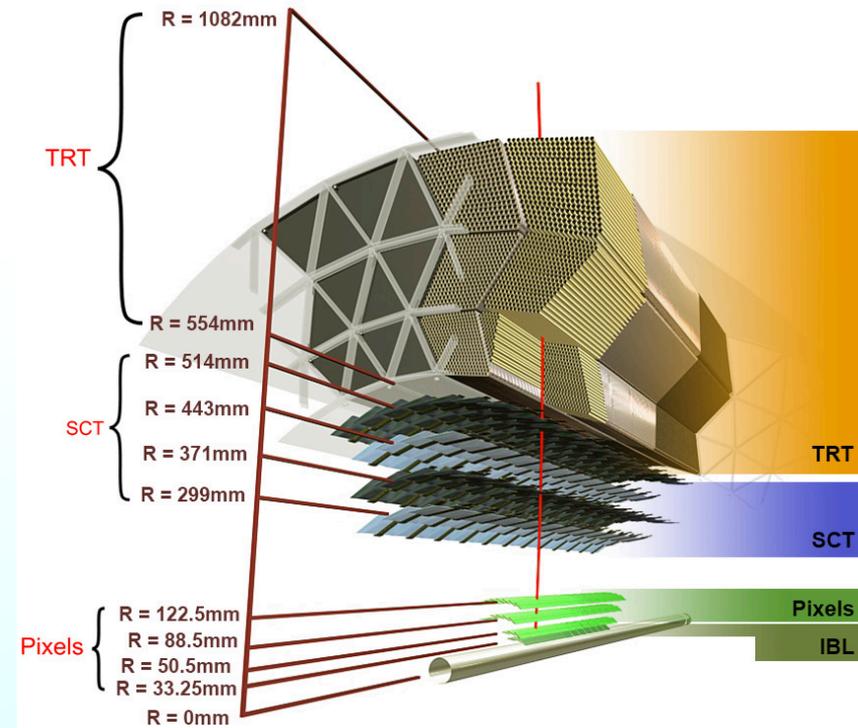
ATLAS DETECTOR

- ❑ Detects particles produced by **proton-proton collisions** in the Large Hadron Collider
- ❑ Studies: origin of mass, nature of dark matter, new physics, quark-gluon plasmas



INNER DETECTOR STRUCTURE

- Inner detector measures charged particle **trajectory**
- Inner tracker radius: ~ 1 m
 - Pixels
 - Semiconductor Tracker
 - Transition Radiation Tracker



ATLAS Inner Tracker

ATL-PHYS-PUB-2015-018

WHAT'S NEXT FOR THE LHC?

2012

$$\sqrt{s} = 7-8 \text{ TeV} \quad L=0.8 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$$

28 fb⁻¹

2013

2014

LS1

First shutdown

2015

2016

$$\sqrt{s} = 13 \text{ TeV} \quad L=1.4 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$$

36 fb⁻¹

2017

EOY



~150 fb⁻¹

2018

$$\sqrt{s} = 13-14 \text{ TeV} \quad L=1.5-1.7 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$$

2019

2020

LS2

Phase 1 upgrade

2021

2022

$$\sqrt{s} = 14 \text{ TeV} \quad L=2 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$$

~300 fb⁻¹

2023

Pileup: 20 – 40

2024

2025

LS3

HL-LHC Phase 2 upgrade

2026

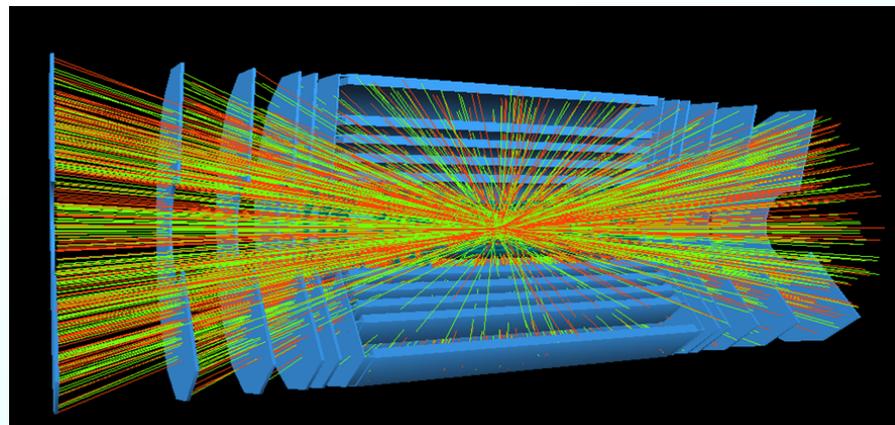
$$\sqrt{s} = 14 \text{ TeV} \quad L=5 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$$

Pileup: 140 – 200

~300 fb⁻¹
/ year

MOTIVATION TO REPLACE INNER DETECTOR

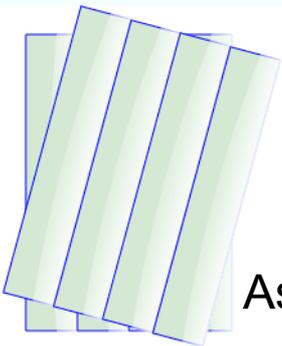
- ❑ Must handle significantly **increased luminosity**
- ❑ **Issues**
 - ❑ Bandwidth saturation
 - ❑ Detector occupancy
 - ❑ Radiation damage
- ❑ Requires a **complete replacement**



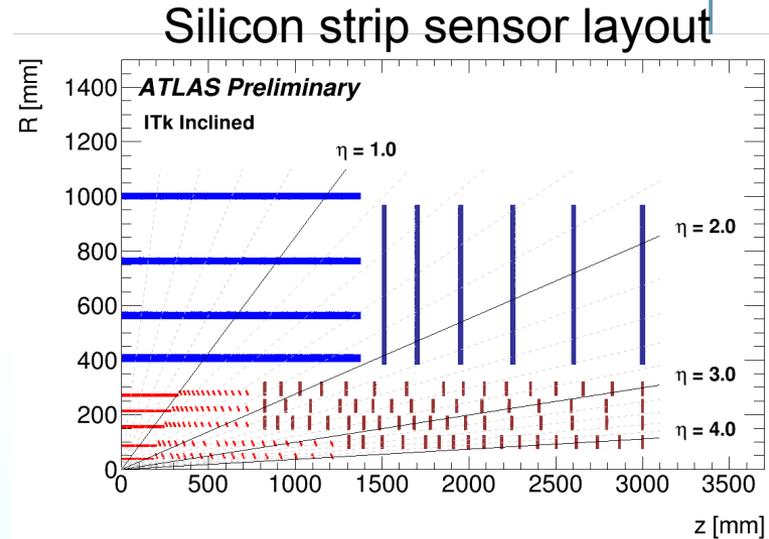
Pileup in the inner detector

BASELINE TECHNOLOGY

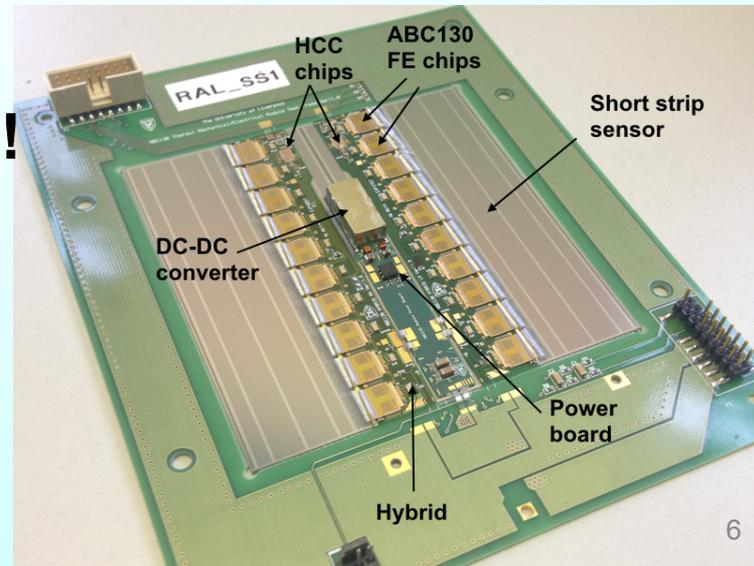
- Plan to replace the inner detector with a new **all-silicon detector**
- **Two detectors**
 - **Pixel detector: 39-271 mm radius**
 - **Silicon strip detector: 405-1000 mm radius**
- **Silicon strips: over 200 m² silicon!**



Assembled silicon strip sensor



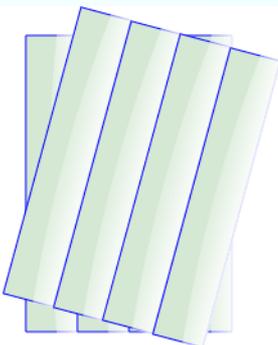
Public Upgrade Inner Tracker ITk Plots <http://dx.doi.org/10.1016/j.nima.2016.03.099>



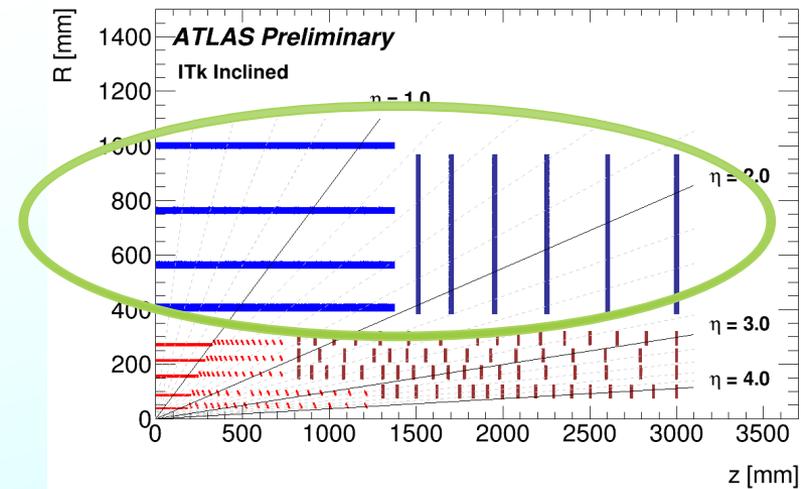
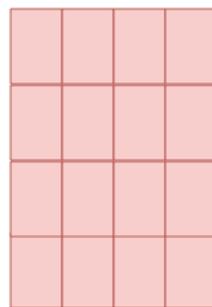
ALTERNATIVE: HIGH-VOLTAGE CMOS DETECTORS

- Alternative proposed sensor technology
- Potential advantages over strip sensors
 - Reduced material budget
 - Assembly time/complexity
 - Commercial fabrication
 - Reduced cost
 - Spatial resolution

Planar silicon



CMOS



Public Upgrade Inner Tracker ITk Plots <http://dx.doi.org/10.1016/j.nima.2016.03.099>

CMOS: FUNDAMENTAL DIFFERENCES

- “**Monolithic**” chip: Readout electronics are **integrated** with the sensor
- Information exchange to readout chips uses **fast digital bus**
 - Far fewer wire bonds than traditional one bond per channel
- Inherently **pixel-like** sensor
 - Row+column readout gives longitudinal information
 - Could reduce silicon area by $\sim 1/2$

STATUS

□ CHESS-1

- Pixel response
- Can the pixels handle **radiation**?
 - Answer: so far, **yes**
- Fadayev et al. characterize HVCMOS after irradiation by **neutrons** and **protons**
 - <http://dx.doi.org/10.1016/j.nima.2016.05.092>
- Mandić et al. with **neutrons**
 - <https://arxiv.org/abs/1701.05033>

• CHESS-2

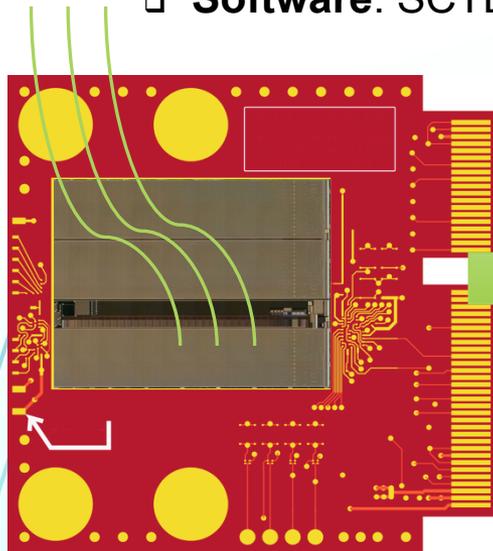
- System Response
- Can we build a **full prototype**?
- Match the planned **readout protocol** and **physical architecture**
- In progress



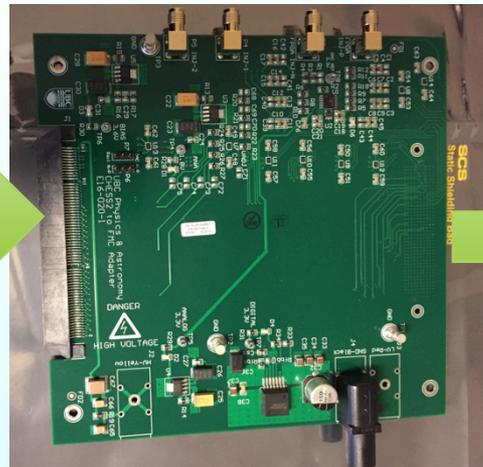
OUR CURRENT WORK

READOUT HARDWARE AND SOFTWARE

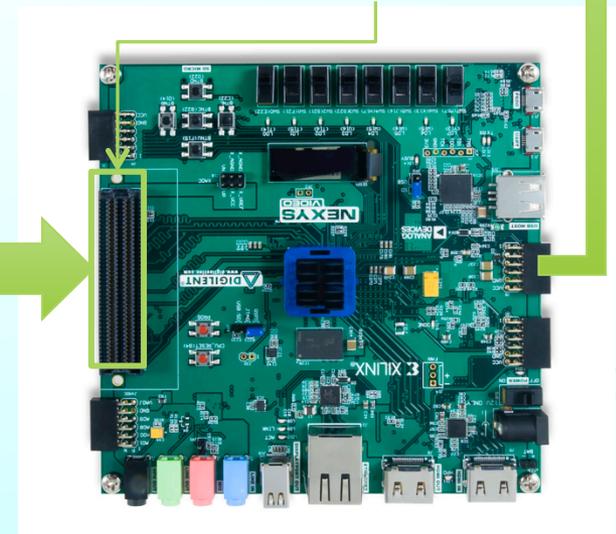
- Full test system will include:
 - CHES-2 **digital daughterboard** designed at SLAC.
 - CHES-2 to **FMC adaptor board** designed at UBC.
 - Supplies power, bias voltage, FMC communication to FPGA
 - Data acquisition (**DAQ**) board: Digilent's Nexys Video FPGA
 - **Firmware**: ITSDAQ (ITk Strips Data acquisition)
 - **Software**: SCTDAQ (SemiConductor Tracker Data acquisition)



Digital Daughterboard



Adaptor board



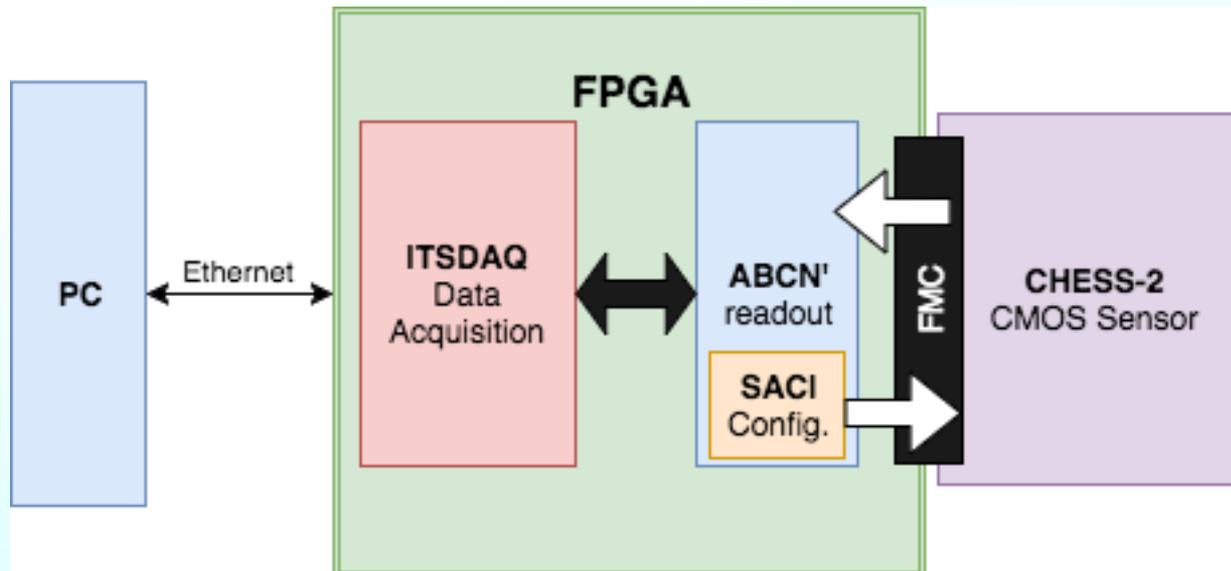
Nexys Video FPGA

FMC
FPGA Mezzanine Card

MY ROLE

READOUT SOFTWARE AND FIRMWARE

- Develop robust communication package for **configuration and data readout**
- Developing firmware to communicate with the ASIC control
- Use existing **SACI communication** protocol to define packet contents



NEXT STEPS

- Completion and testing of **readout software**
- **Integration** into the current mechanical and electrical system (a full module)
- Examination of signal response with **charge injection** on CHESS sensor (simulating signals)
- Single chip **ASIC** to replace FPGA prototype

SUMMARY

- ATLAS inner tracker will be replaced to **cope with high-radiation** environment of High-Luminosity LHC program
- High Voltage **CMOS sensors** are proposed as an alternative to the baseline silicon strip sensors
- CHESS-2 program will construct a **fully integrated prototype** for testing and proof-of-concept
- Readout software and firmware being constructed as to be **compatible with planned ITk readout infrastructure**

The slide features a light blue gradient background. In the corners, there are decorative elements consisting of thin blue lines that resemble circuit traces or a network diagram, ending in small white circles. These elements are located in the top-left, top-right, and bottom-left corners, with a partial one in the bottom-right.

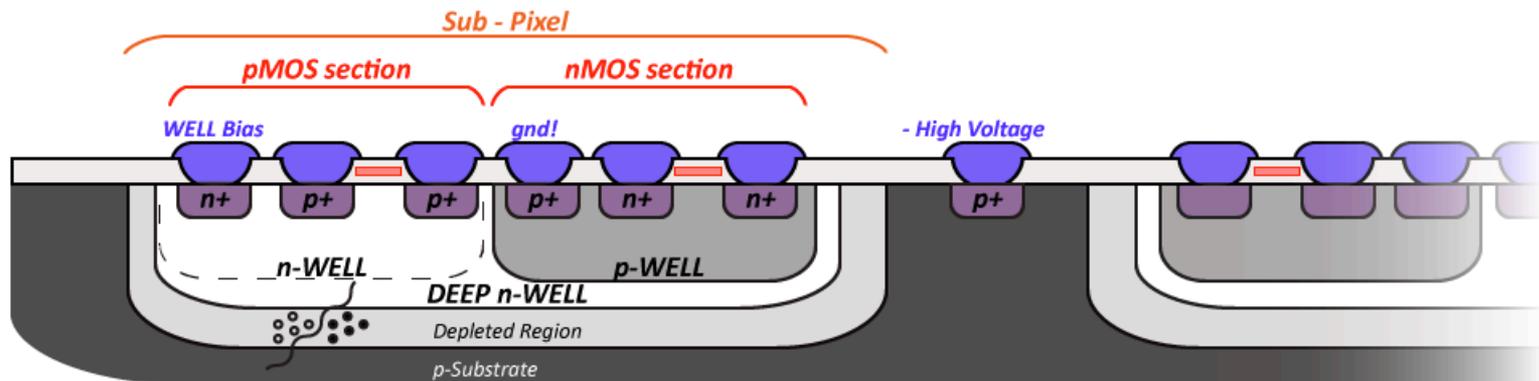
QUESTIONS?

BACKUP SLIDES

CHESS-2 CROSS SECTION

- ❑ CHESS-2: “CMOS HV/HR Evaluation for Strip Sensors”
- ❑ **Electron-hole pairs** (caused by ionizing particles) separated and quickly collected by drift
- ❑ A lightly doped deep n-well (DNW) in p-type substrate is used as charge collecting electrode
- ❑ The p-n junction is partially depleted by applying a reversed bias voltage

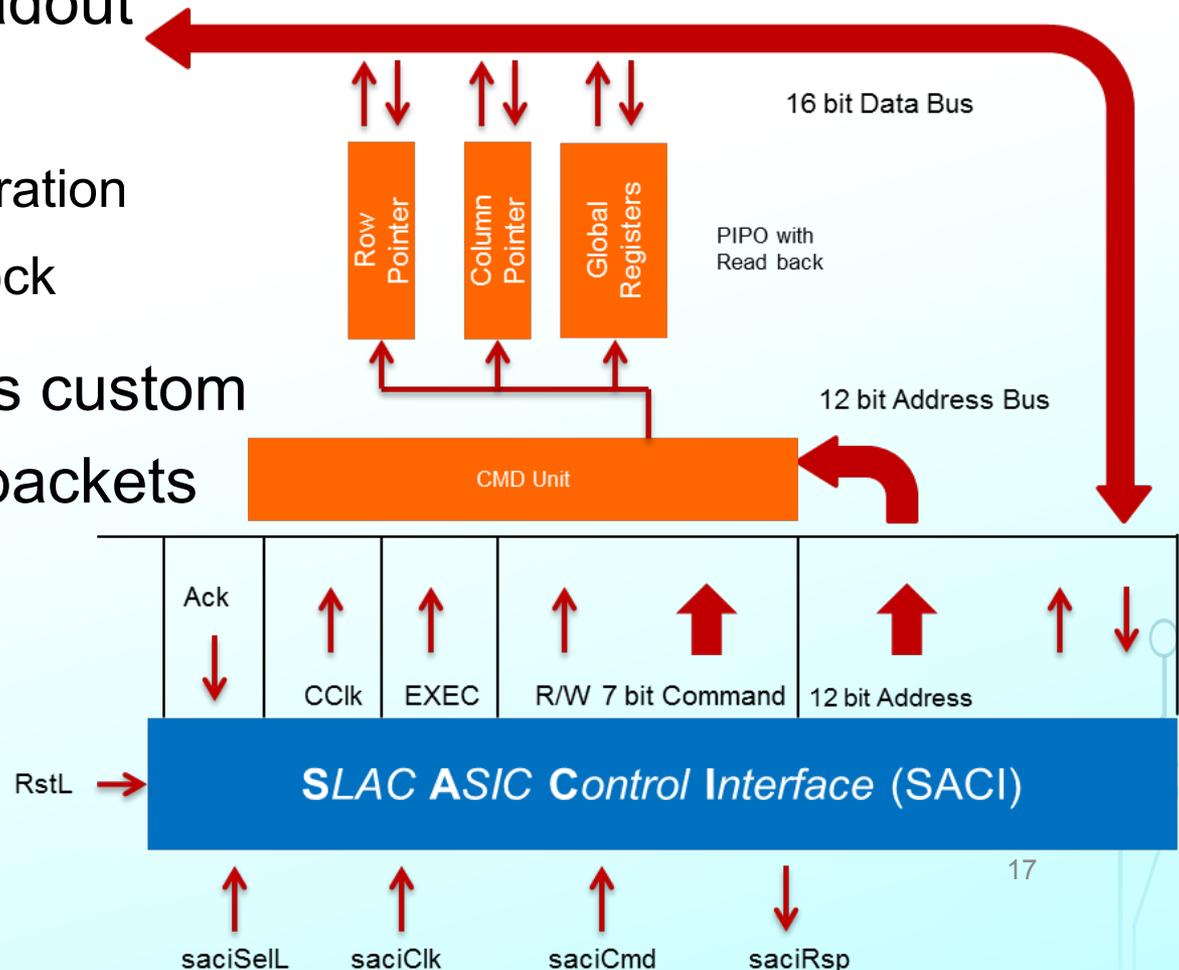
<http://iopscience.iop.org/article/10.1088/1748-0221/10/03/C03033>



AMS 0.35 μ m HV Sensor and read-out on the same substrate.

SACI COMMAND STRUCTURE (SLAC ASIC CONTROL INTERFACE)

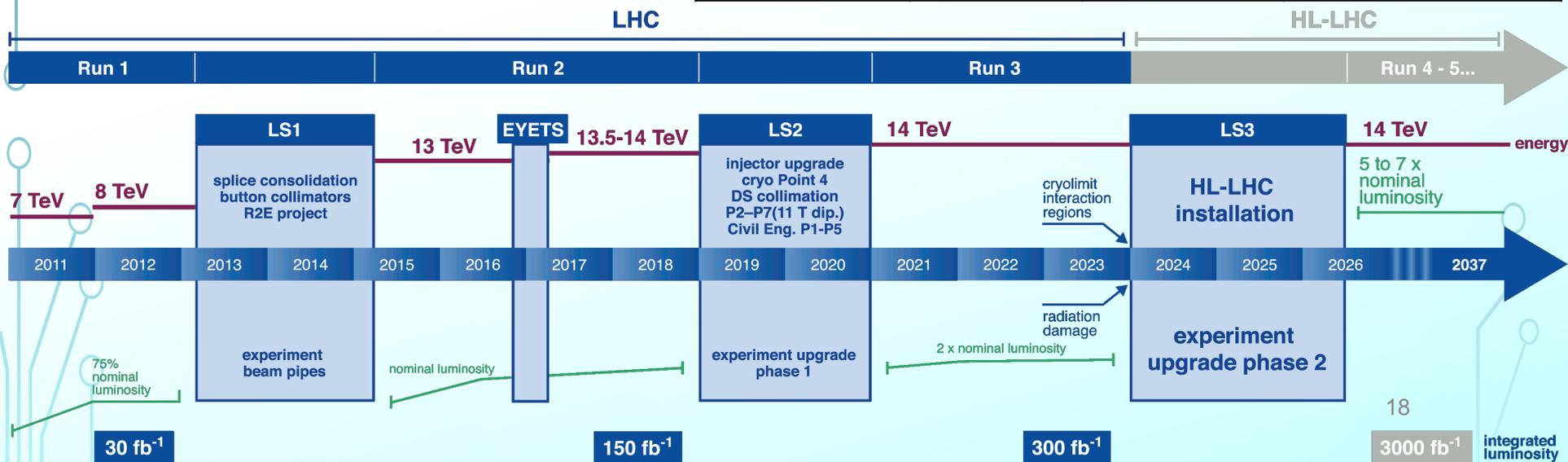
- SACI configures readout electronics
 - Pixel matrix configuration
 - Initialize 40MHz Clock
- Instructions come as custom serialized ethernet packets



NEXT STEPS FOR ATLAS

- High-Luminosity LHC upgrades will increase the dataset

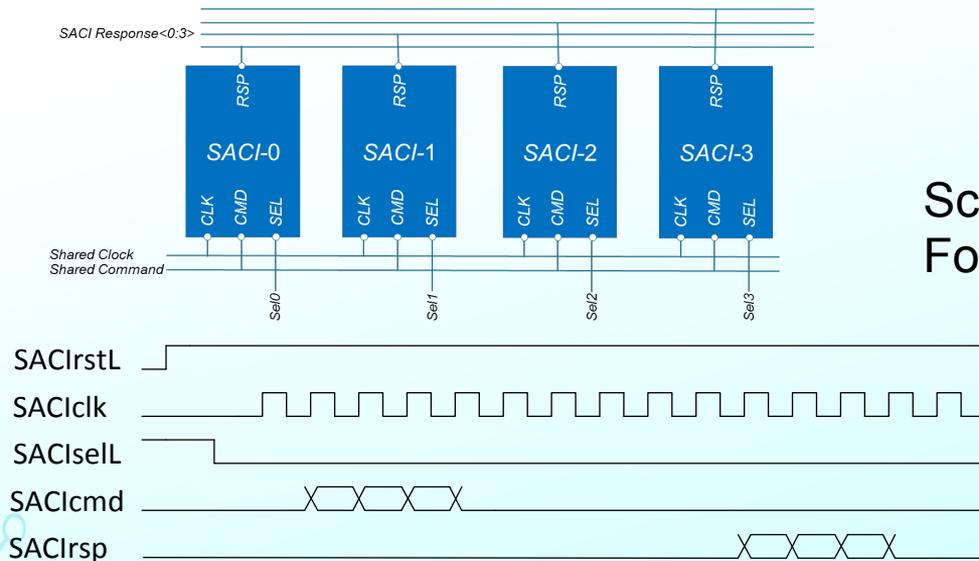
Year: Run	CoM Energy (TeV)	Integrated Luminosity (fb ⁻¹)	Instantaneous Luminosity (cm ⁻² s ⁻¹)
2010: Run 1	7	~30	8x10 ³³ (2012)
2017: Run 2	13	~150	1.37x10 ³⁴ (2016)
2020: Run 3	14	~300	2x10 ³⁴
2025: HL-LHC	14	~3000	5-7x10 ³⁴



OUR CURRENT WORK

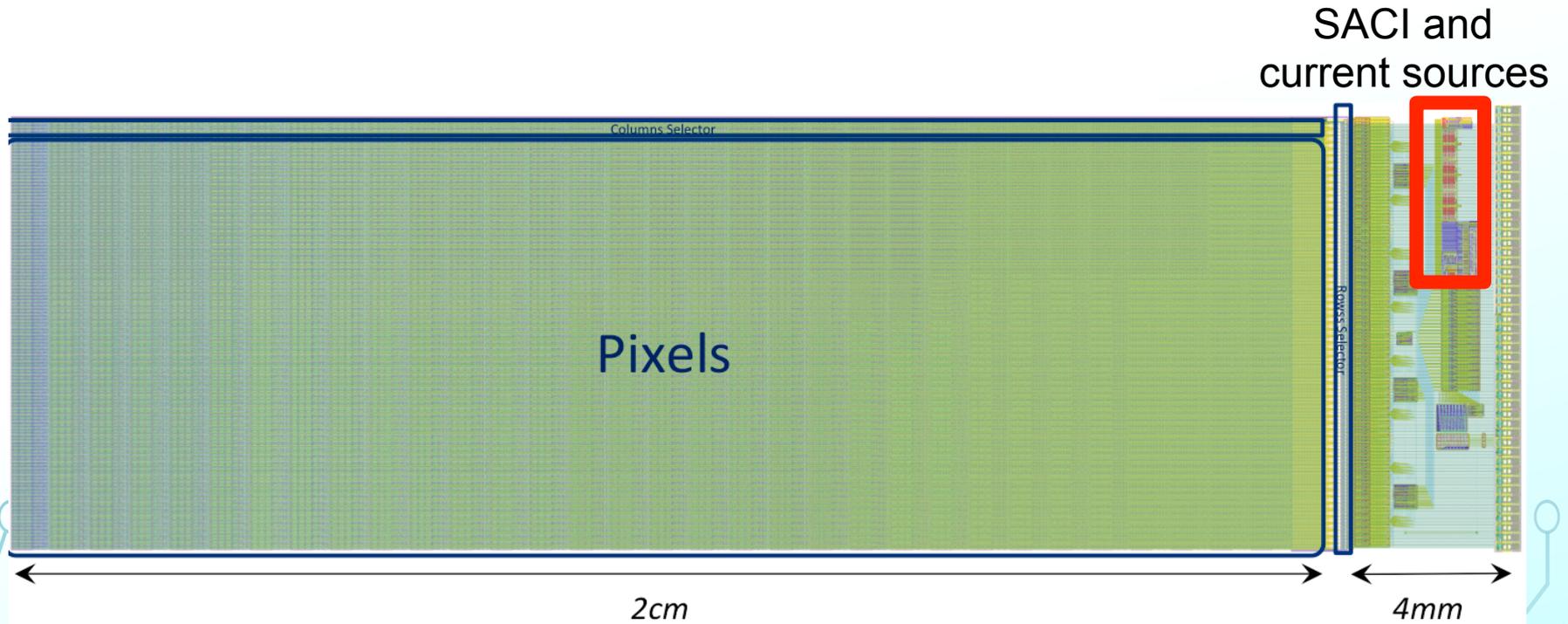
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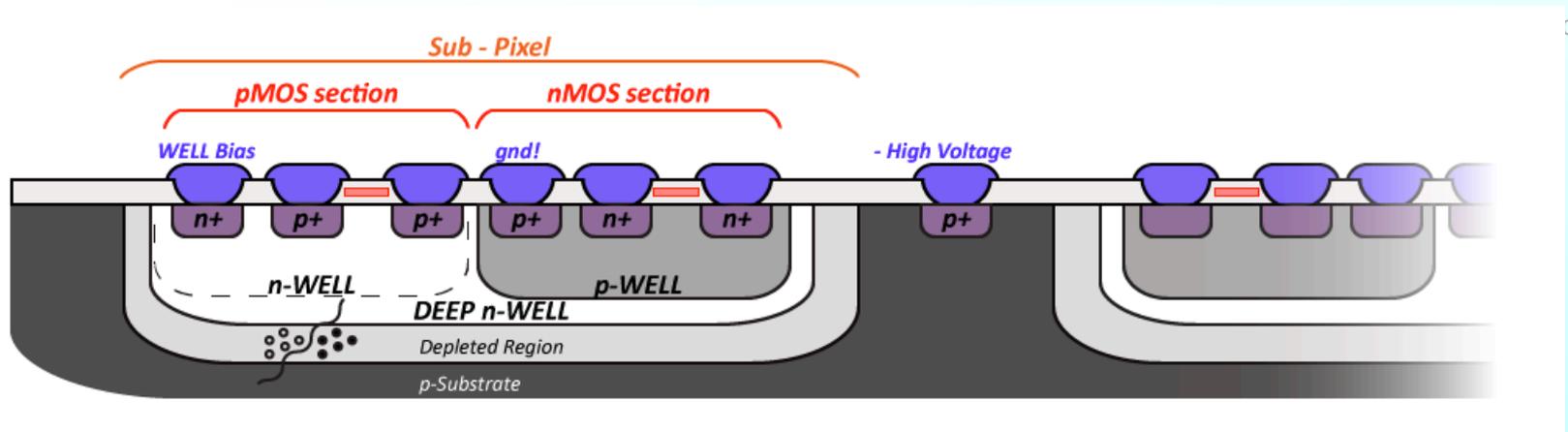
Schematic and example signals
For SACI configuration commands

CHESS-2 PHYSICAL STRUCTURE



CHESS-2 CROSS SECTION

- ❑ CHESS-2: “CMOS HV/HR Evaluation for Strip Sensors”
- ❑ Sensor is based on a **triple-well structure**
- ❑ A lightly doped deep n-well (DNW) in p-type substrate is used as charge collecting electrode
- ❑ The p-n junction is partially depleted by applying a reversed bias voltage
- ❑ Electron-hole pairs (caused by ionizing particles) separated and quickly collected by drift



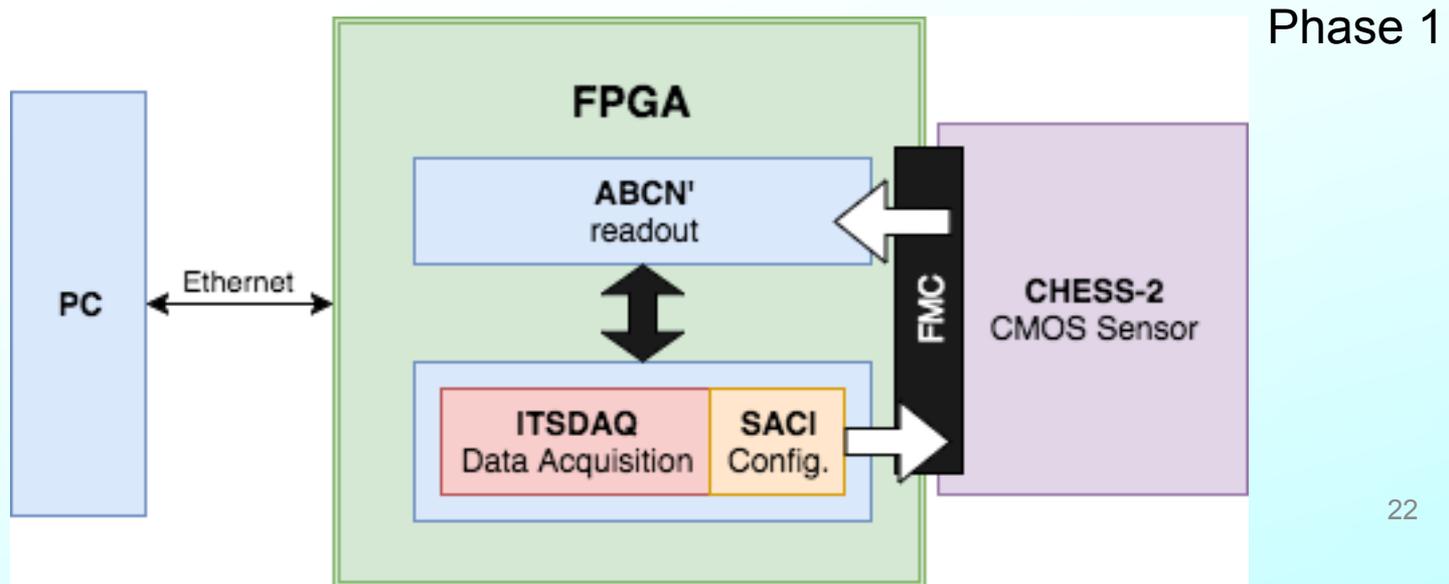
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